

Cooling and/or lubricating fluids for wafer production

Abstract

- 5 The invention relates to the use of modified polyglycols for production of cooling and/or lubricating fluids, to novel cooling and/or lubricating fluids, to the use of the cooling and/or lubricating fluids in the removal of material, especially in the cutting of wafers, and to wafers produced with the aid of the cutting fluid.